

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3959949

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the THE NAME OF THE RECEIVING PARTY DATA FROM TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD previously recorded on Reel 038188 Frame 0989. Assignor(s) hereby confirms the RECEIVING PARTY DATA NAME BE CHANGED TO TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
RESUBMIT DOCUMENT ID:	503780221

CONVEYING PARTY DATA

Name	Execution Date
YUNG-SUNG YEN	03/21/2016
RU-GUN LIU	03/23/2016
WEI-LIANG LIN	03/21/2016
HSIN-CHIH CHEN	03/22/2016

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN ROAD 6,
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15072792

CORRESPONDENCE DATA

Fax Number: (214)651-5940

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.3345US01
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NAME OF SUBMITTER:	LADONNA JOHNSON
SIGNATURE:	/LADONNA JOHNSON/
DATE SIGNED:	07/13/2016
Total Attachments: 7 source=24061.3345US01 (PP20151413US00) - Start Resubmission of Corrective Assignment#page1.tif source=24061.3345US01 (PP20151413US00) - Start Resubmission of Corrective Assignment#page2.tif source=24061.3345US01 (PP20151413US00) - Start Resubmission of Corrective Assignment#page3.tif source=24061.3345US01 (PP20151413US00) - Start Resubmission of Corrective Assignment#page4.tif source=24061.3345US01 (PP20151413US00) - Start Resubmission of Corrective Assignment#page5.tif source=24061.3345US01 (PP20151413US00) - Start Resubmission of Corrective Assignment#page6.tif source=24061.3345US01 (PP20151413US00) - Start Resubmission of Corrective Assignment#page7.tif	

503780221 04/12/2016

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3826867

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the THE NAME OF THE RECEIVING PARTY DATA FROM TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. previously recorded on Reel 038188 Frame 0989. Assignor(s) hereby confirms the RECEIVING PARTY DATA NAME BE CHANGED TO TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD..
CONVEYING PARTY DATA	
Name	Execution Date
YUNG-SUNG YEN	03/21/2016
RU-GUN LIU	03/23/2016
WEI-LIANG LIN	03/21/2016
HSIN-CHIH CHEN	03/22/2016
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN ROAD 6,
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15072792
CORRESPONDENCE DATA	
Fax Number:	(214)651-5940
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Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.3345US01
NAME OF SUBMITTER:	LADONNA JOHNSON

Docket No.: P20151413US00/24061.3345US01
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|--|
| (1) | Yung-Sung Yen | of | Chiayi County, Taiwan, Republic of China |
| (2) | Ru-Gun Liu | of | Miaoli County, Taiwan, Republic of China |
| (3) | Wei-Liang Lin | of | Hsin-Chu, Taiwan, Republic of China |
| (4) | Hsin-Chih Chen | of | Hsinchu, Taiwan, Republic of China |

have invented certain improvements in

A METHOD OF PLANARIZATING A FILM LAYER

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on and assigned application number ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and

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Customer No.: 000042717

testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yung-Sung Yen

Residence Address: 4F., No. 15-3, Alley 2, Lane 85, Minsheng Street, Zhonghe District
New Taipei City 235, Taiwan, Republic of China.

Dated: 2016/03/21

Yung-Sung Yen
Inventor Signature

Inventor Name: Ru-Gun Liu

Residence Address: No. 90, Chenggong 5th Street, Zhubei City
Hsinchu County 302, Taiwan, Republic of China

Dated: 23 Mar. 2016

Ru-Gun Liu
Inventor Signature

Inventor Name: Wei-Liang Lin

Residence Address: 4F., No. 11, 7 Alley, 384 Lane, 1st Section
Chun-Hua Road, Hsin-Chu City, Republic of China

Dated: 2016/03/21

Wei-Liang Lin
Inventor Signature

Inventor Name: Hsin-Chih Chen

Residence Address: 6F., No. 8, Lane 24, Syueshih Road, Tucheng City
Taipei County 236, Taiwan, Republic of China

Dated: 3/22/2016

Hsin-Chih Chen
Inventor Signature